



# ***Geant4 + TCAD: An Application Example***

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(G4SUW2013)**

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# Scope

- This is an introductory presentation prepared for those who already know about Geant4...  
... but are newcomers for SEE analysis and prediction.
- We use a Geant4 application developed in our group to show some issues that a new user may find with FASTRAD, Geant4, GDML and TCAD.
  - In other words, this talk tries to present some things that one would like to hear about when starting an application development.
- Introduction of developments to extend Geant4 capabilities and TCAD analysis, presented in the next sessions.



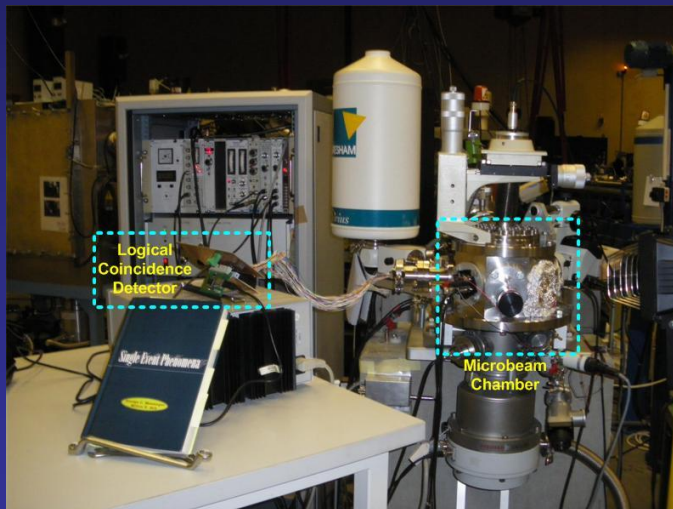
# Outline

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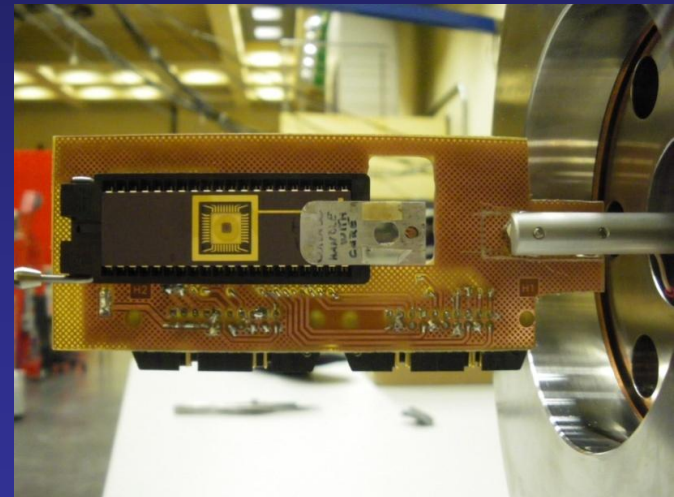
- Introduction
- Geometry modelization with FASTRAD
- Main features of our Geant4 application
- Getting Geant4 charge distribution for TCAD
- Charge distribution model in Sentaurus TCAD and ATLAS Silvaco (*de-facto* standards)
- Proposed improvements

# Introduction

- We present a GEANT4 approach to simulate the incidence of charged particles on a CMOS flip-flop designed according to AMIS C5 rules.
  - **Protons** (18 MeV) and **deuterons** (9 MeV) produced at IBA-CNA cyclotron (Seville, Spain).
  - **Ion beams** produced at the 3-MV tandem accelerator present at the CNA facility as well.



Experiment data acquisition (\*)



Target (\*)

(\*) Courtesy of F. Rogelio Palomo (Univ. Seville)

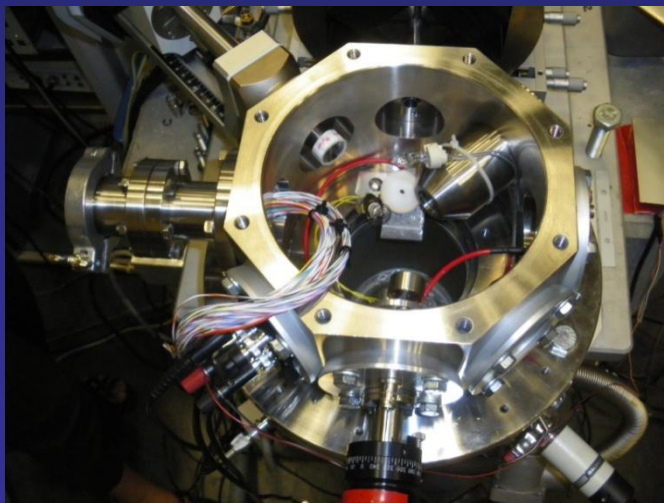
# The CNA facility in Seville



3 MV Tandem Van de Graaf Accelerator



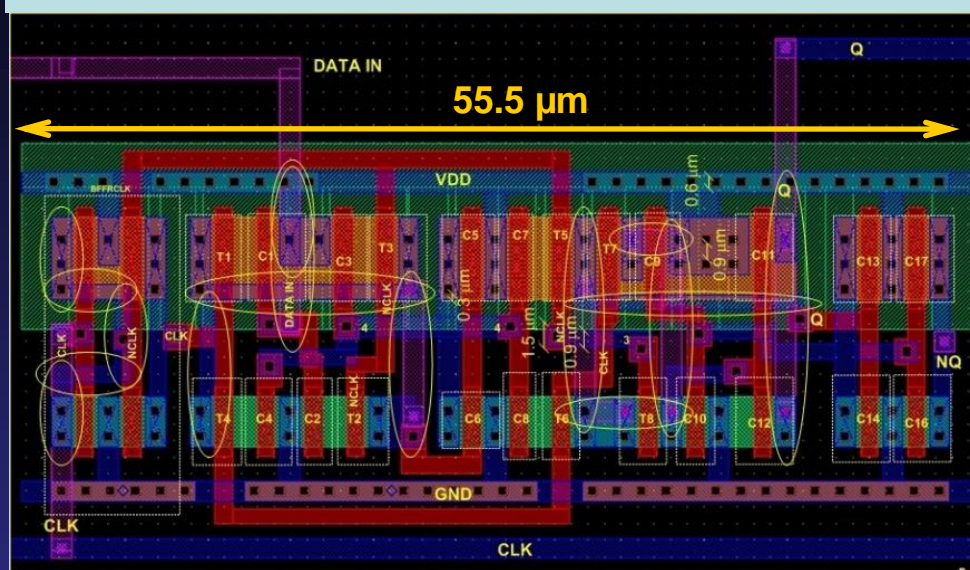
IBA-CNA cyclotron



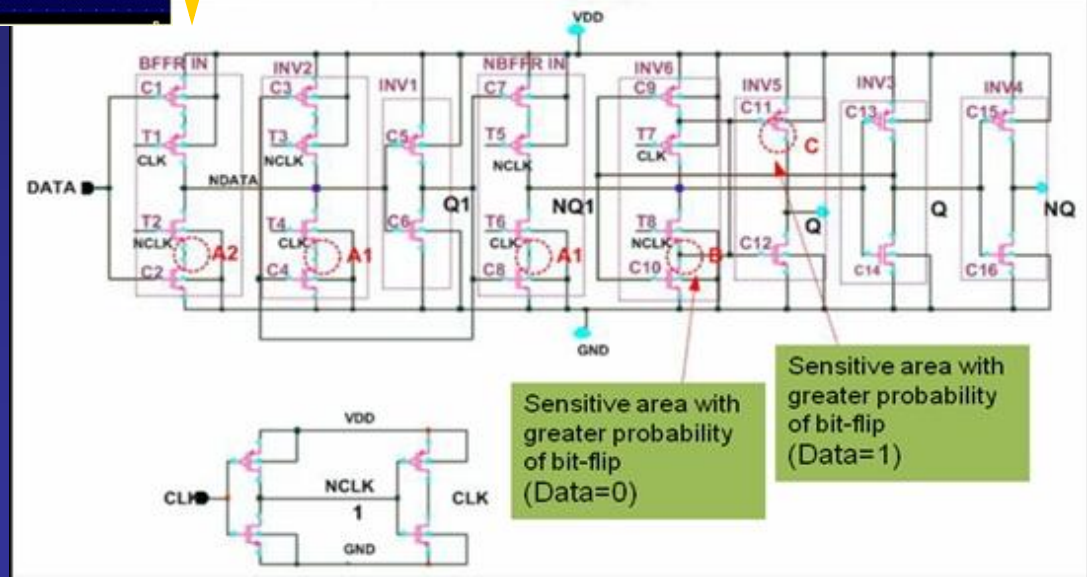
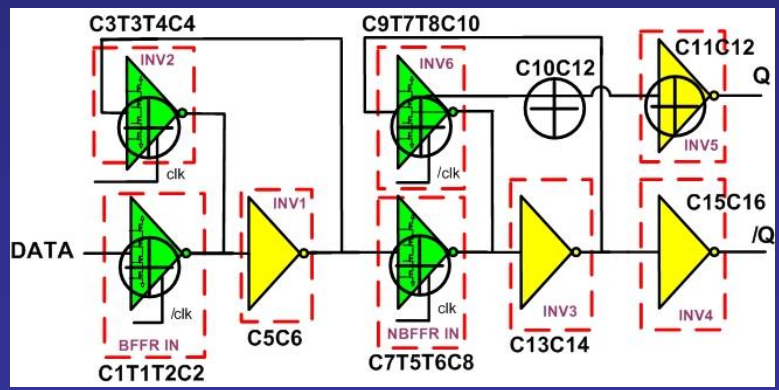
Microbeam chamber

( <http://www.cna.us.es> )

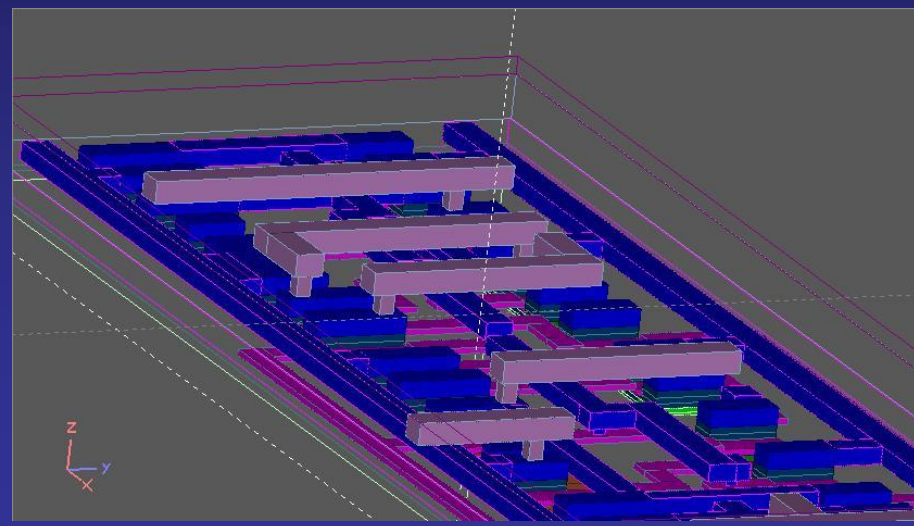
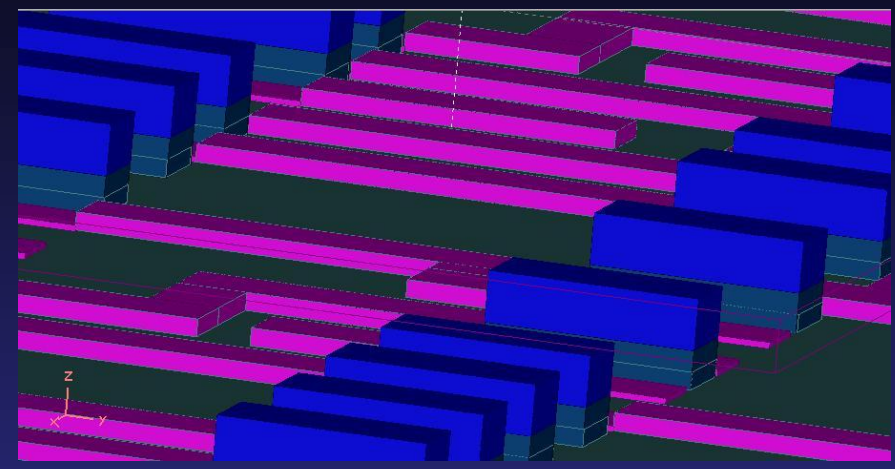
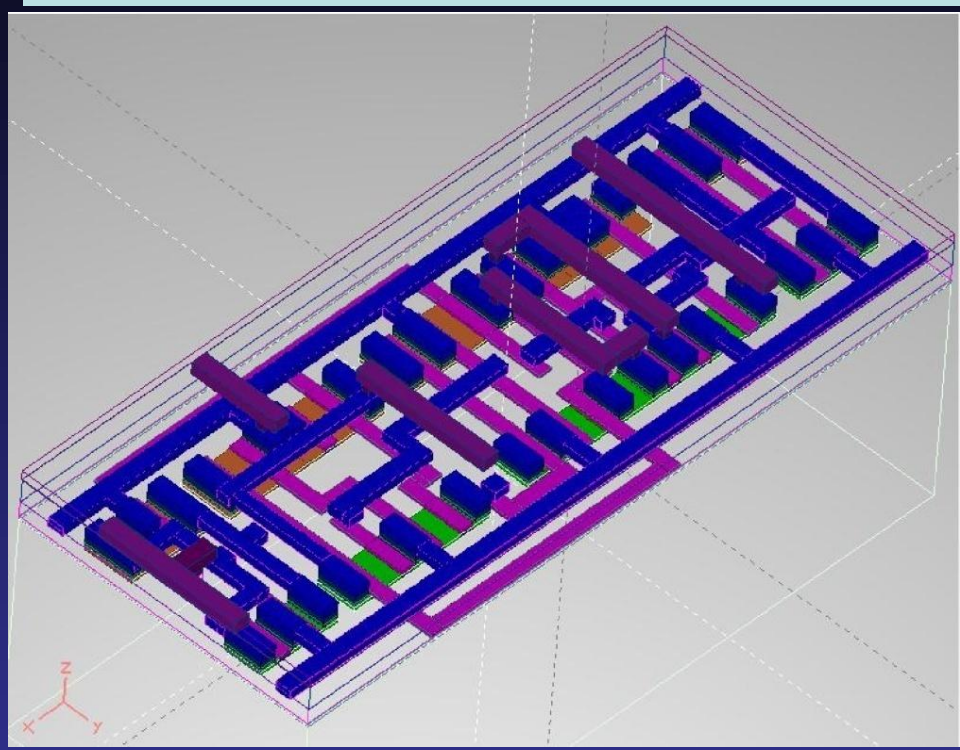
# Flip-Flop Schematics & Design



Master-slave flip-flop (AMIS C5) and clock buffer, comprised of 28 transistors in total.



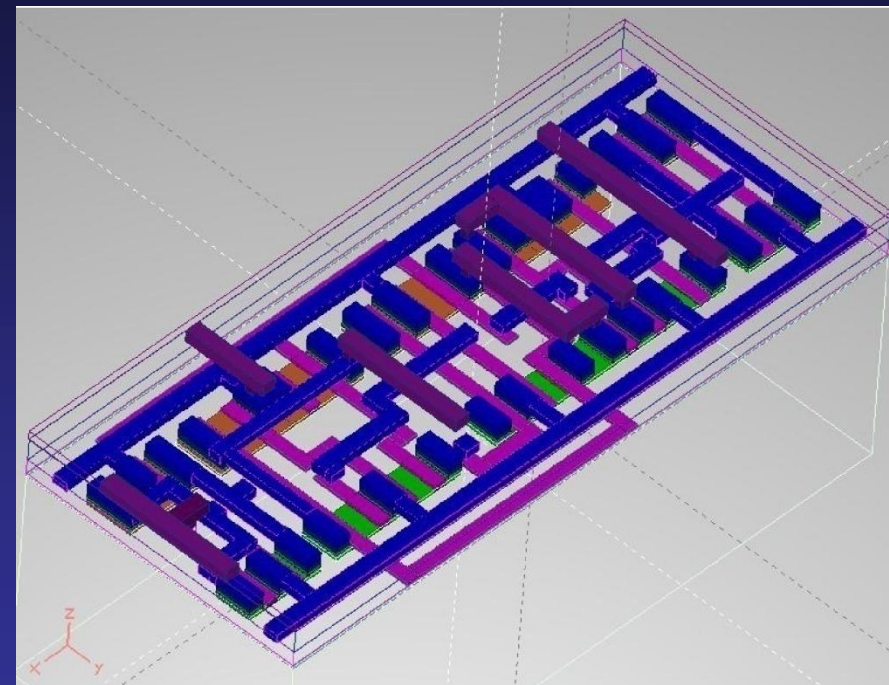
# FASTRAD Model of the Flip-Flop



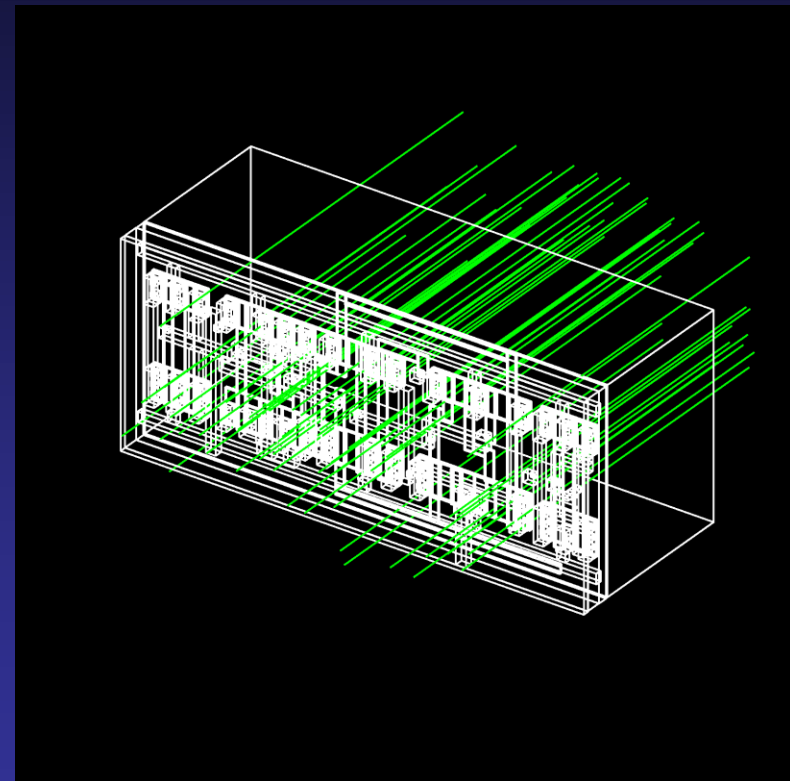
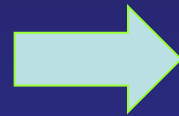
- **Non-overlapping volumes nor mother-daughter hierarchy.**
- **Trenches** must be modeled in the substrate prior placing components.
- Model scaled **from microns to mm** for clarity.

# Conversion to a Geant4 Geometry Model

- **FASTRAD exports XML files readable by Geant4 using the GDML schema<sup>(\*)</sup>**



**FASTRAD model**



**GEANT4 model**

<sup>(\*)</sup> **GDML:** R. Chytrcek et al., *IEEE-TNS 53*: 2892 (2006)





# Geant4 Application for the Irradiation of the Flip-Flop

- **Aims:**

- Score the **energy deposition** in elements of a flip-flop.
- Geometry imported from **GDML** using G4GDMLParser (see persistency/gdml extended examples).
- Regions and sensitive detectors defined with user-defined commands passing the Logical Volume (LV) name, such as:
  - **/mygeom/sdName "a LV name"**
  - **/mygeom/detailedReg "a LV name"**

- **Some needs in Detector Construction:**

- Vectors to store the strings passed in the macro commands.
- LV identification by name using **G4LogicalVolumeStore** singleton (or similar approach using **GDMLAuxPairType** classes).



# The Geant4 Application: DetectorConstruction Class

- However, LV names given by GDML output of FASTRAD follows an automatic logic:
  - [name]\_[a number]\_Volume
    - (example: “Oxide\_365\_Volume”)
- Thus, LV identification by name becomes an issue when using copies of the same solid in FASTRAD.
- **A possible solution is:**
  - Use **G4LogicalVolumeStore** singleton to make a list of LV names.
  - Create a database (a table) where each LV is identified with a component of the flip-flop (according to the coordinates, solid dimensions, etc.)
  - Define geometry features (regions, SD's) according to our needs.



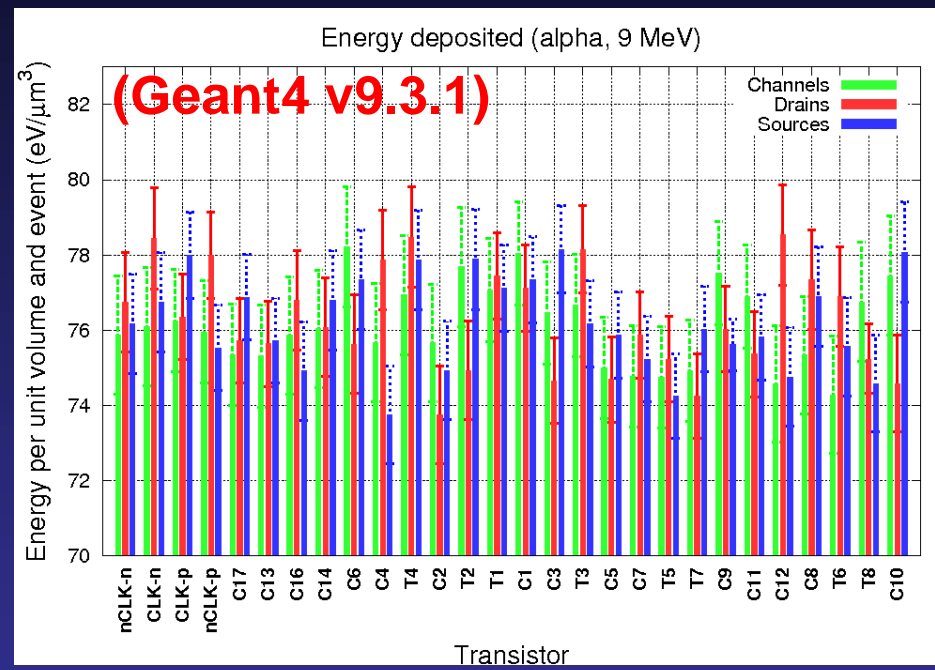
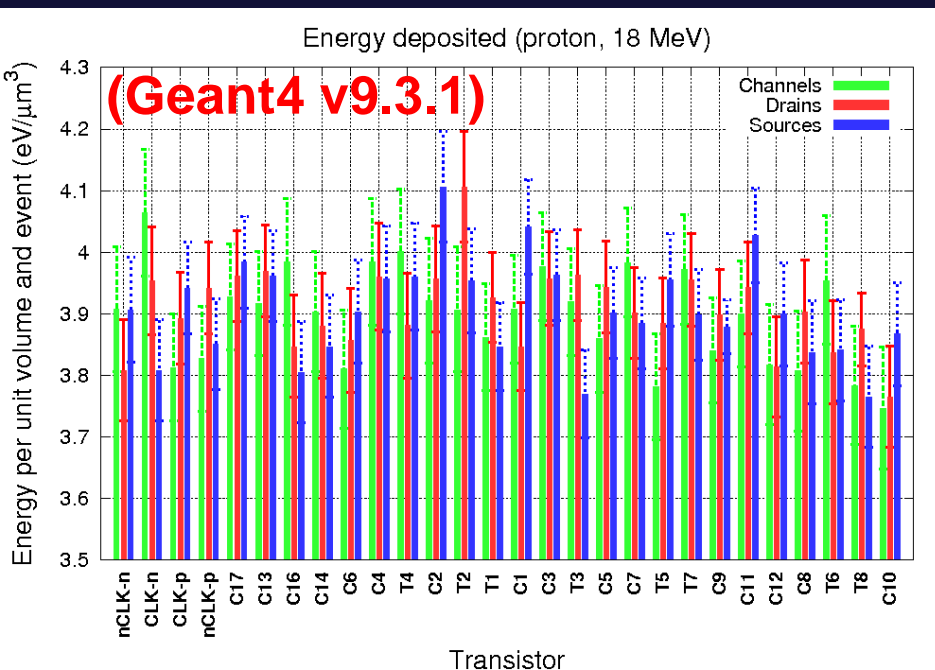
# The Geant4 Application: DetectorConstruction Class

**Example: Scoring energy deposition in the channel, drain and source of each transistor.**

- User-defined commands:
  - /mygeom/sdName Channel
  - /mygeom/sdName Drain
  - /mygeom/sdName Source
- In the `Construct()` method, register an energy deposition scorer to each LV which name **contains** one of the strings passed in the commands.
- For each string, the SD's are registered in the same order as they appear in the list of LVs made from **G4LogicalVolumeStore**.
- From **G4SDManager** singleton we can retrieve the list of SD's registered, which must follow the same order as in `G4LogicalVolumeStore`. Same applies for the hit maps (or hit collections) dumped into an output file.

# The Geant4 Application: Results. Energy Deposition.

## Irradiation of the flip-flop with heavy-charged particles

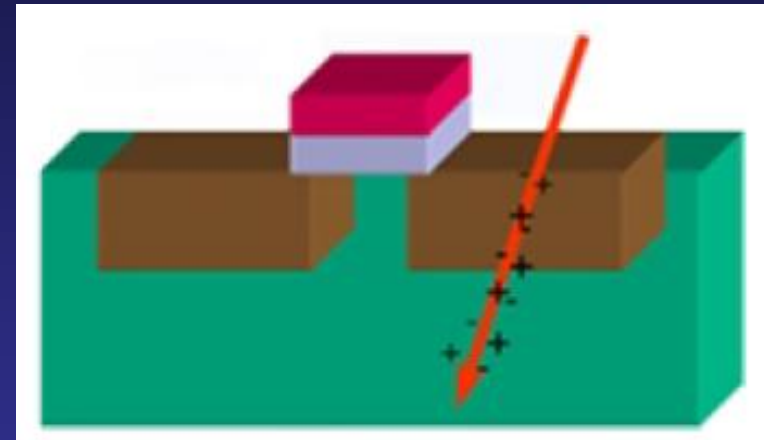


- Uniform irradiation condition has been considered.
- This detail level helps to study which structures are more vulnerable against the incidence of charged particles.

M.A. Cortés-Giraldo et al., *Progress in Nucl. Sci. Technol.* 2: 509-515 (2011)

# Geant4 Charge Distribution for TCAD

- The flip-flop application calculates the **energy deposition averaged over the entire volume**.
- This approach is enough if we are interested in accumulative damages.
- But, for SEE studies this is not enough because of high gradients in energy deposition.
- An **application for track structure analysis** is created to calculate a model of energy deposition in depth.

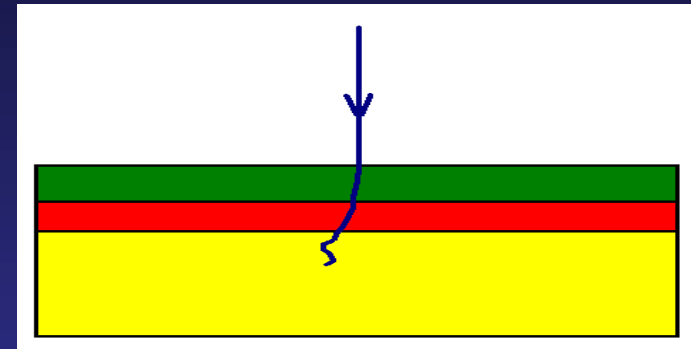


# “Track Analysis” Application

- Developed to analyze charged-particle **track structure**.
- Two approaches:

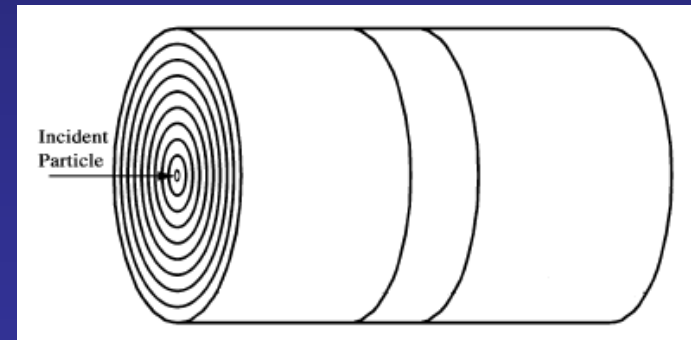
- **LET calculation:**

Particle incidence on a layered geometry (SRIM geometry)



- **Radial dose distribution:**

Particle incidence on a “bullseye” geometry (\*)

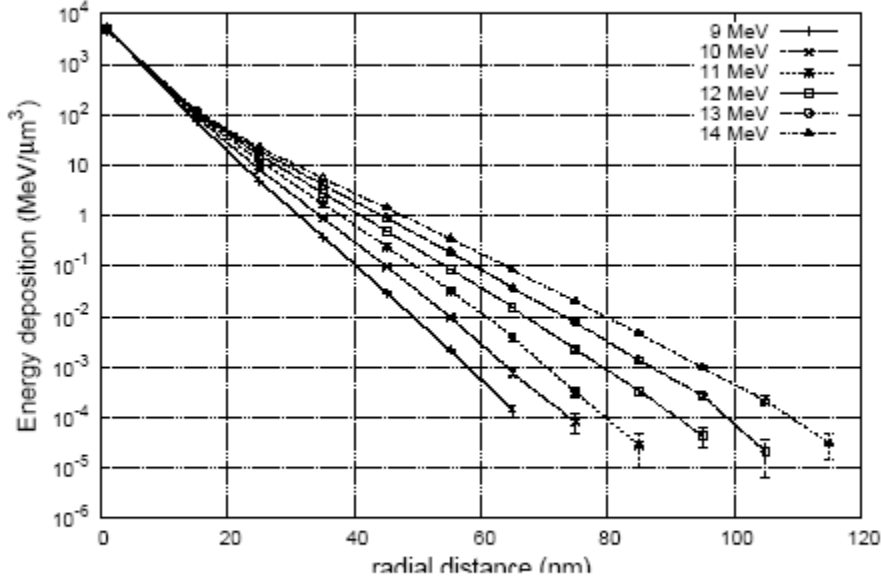


(\*) Geometry similar to A.S. Kobayashi et al., *IEEE-TNS* 51: 3312 (2004)

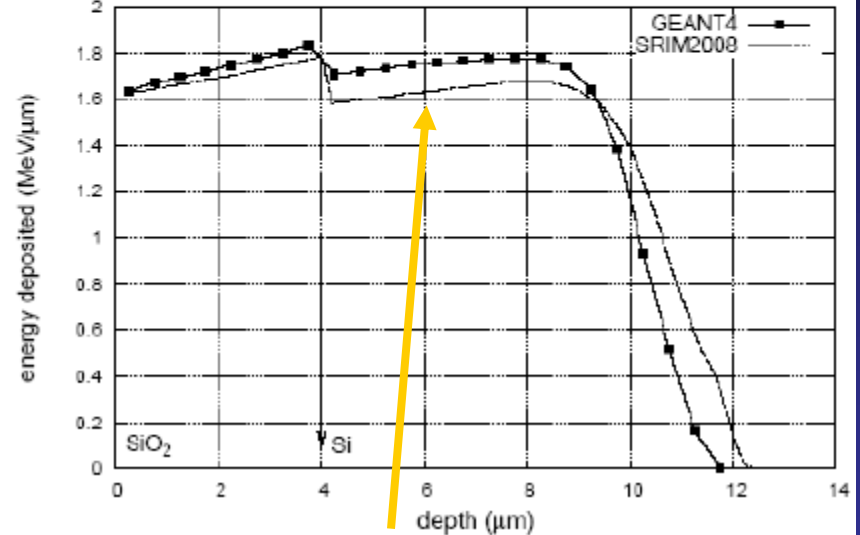
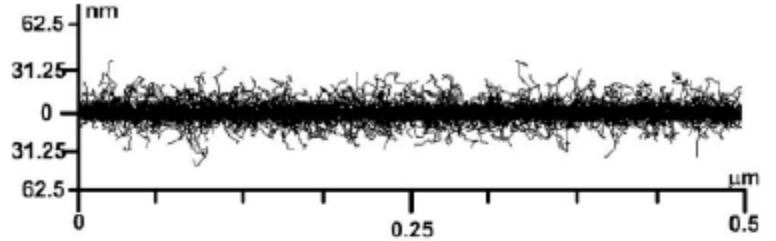
# Track Analysis: Results

(Geant4 v9.3.1)

Energy deposition per unit volume (O ions in Si)



$$LET(d)_{\text{electronic}} = 2\pi \int_0^R r dr D(r, d)$$



Within Geant4 EM model accuracy (~ 10%)

M.A. Cortés-Giraldo et al., *Progress in Nucl. Sci. Technol.* 2: 509-515 (2011)



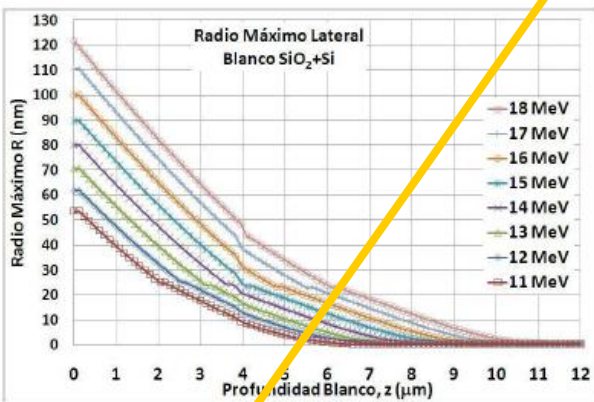
# *Developments in Geant4 at very low energies for Microdosimetry*

- Geant4 **Standard** and **Livermore** EM packages are reliable for electrons down to  $\sim 0.1-1.0$  keV.
- Extensions with more accurate models at energies below 100 eV for microdosimetry:
  - **The Geant4-DNA Project** (next talk by S. Incerti).
    - Microdosimetry in water, especially developed for radiobiology
  - **The MuElec extension** (following talk by M. Raine).
    - Microdosimetry in silicon

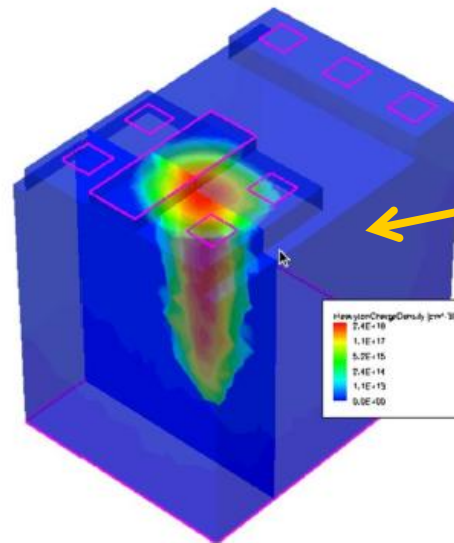


# Charge Distribution Model in Sentaurus TCAD

## Three arrays define the charge distribution model



Considering the whole calculus for the layered target (4 μm SiO<sub>2</sub> +Si) we got the ionization profile inside the transistor target.



Only axial symmetry is foreseen

That results are codified as  $\{z, LET(z), w(z)\}$  in Sentaurus, because the ionization track profile is the data input for transient analysis (in this case, full spectra of oxygen ions from CNA, 11 to 18 MeV with a 1 MeV step).

(\*) Courtesy of F. Rogelio Palomo (Univ. Seville)



# *New Tools for SEE Analysis and Prediction*

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- Have a look to this afternoon's presentations:
  - **MRED** (ISDE/Vanderbilt University)
  - **NanoTCAD** (CFD Research Corp.)
  - **RunSEU** (Cogenda Pte Ltd.)
  - **MINIMOS-NT** (Kallisto Consultancy Ltd.)
  - **CODES** (LIP/ESA)

# Conclusions

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- Use of Geant4 to calculate energy deposition in the components of a *flip-flop* microelectronic device.
  - Such outcomes are very hard to measure.
- The Geant4 usual physics list include EM models which accuracy is not that high for low energy track structure and  $\delta$ -ray transport.
  - See Geant4 extensions in next talks.
- Also, commercial TCAD software present limited options to simulate charge distributions for SEE predictions.
  - Lot of work ongoing by several research groups.



# Acknowledgements

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**THANKS FOR YOUR ATTENTION**